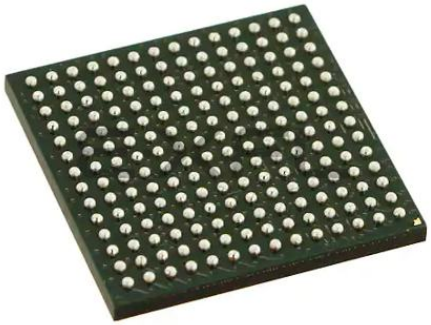


Welcome to E-XFL.COM

Understanding Embedded - DSP (Digital Signal Processors)

Embedded - DSP (Digital Signal Processors) are specialized microprocessors designed to perform complex mathematical computations on digital signals in real-time. Unlike general-purpose processors, DSPs are optimized for high-speed numeric processing tasks, making them ideal for applications that require efficient and precise manipulation of digital data. These processors are fundamental in converting and processing signals in various forms, including audio, video, and communication signals, ensuring that data is accurately interpreted and utilized in embedded systems.

Applications of Embedded - DSP (Digital Signal Processors)

Details	
Product Status	Obsolete
Type	Fixed Point
Interface	Host Interface, SSI, SCI
Clock Rate	100MHz
Non-Volatile Memory	ROM (576B)
On-Chip RAM	24kB
Voltage - I/O	3.30V
Voltage - Core	3.30V
Operating Temperature	-40°C ~ 105°C (TJ)
Mounting Type	Surface Mount
Package / Case	196-LBGA
Supplier Device Package	196-LBGA (15x15)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/spakxc309vl100a

Table of Contents

Data Sheet Conventions

$\overline{\text{OVERBAR}}$	Used to indicate a signal that is active when pulled low (For example, the $\overline{\text{RESET}}$ pin is active when low.)
“asserted”	Means that a high true (active high) signal is high or that a low true (active low) signal is low
“deasserted”	Means that a high true (active high) signal is low or that a low true (active low) signal is high

Examples:

Signal/Symbol	Logic State	Signal State	Voltage
$\overline{\text{PIN}}$	True	Asserted	V_{IL}/V_{OL}
$\overline{\text{PIN}}$	False	Deasserted	V_{IH}/V_{OH}
PIN	True	Asserted	V_{IH}/V_{OH}
PIN	False	Deasserted	V_{IL}/V_{OL}

Note: Values for V_{IL}, V_{OL}, V_{IH}, and V_{OH} are defined by individual product specifications.

1.4 Clock

Table 1-4. Clock Signals

Signal Name	Type	State During Reset	Signal Description
EXTAL	Input	Input	**External Clock/Crystal Input**—Interfaces the internal crystal oscillator input to an external crystal or an external clock.
XTAL	Output	Chip-driven	**Crystal Output**—Connects the internal crystal oscillator output to an external crystal. If an external clock is used, leave XTAL unconnected.

1.5 PLL

Table 1-5. Phase-Locked Loop Signals

Signal Name	Type	State During Reset	Signal Description
CLKOUT	Output	Chip-driven	**Clock Output—**Provides an output clock synchronized to the internal core clock phase. If the PLL is enabled and both the multiplication and division factors equal one, then CLKOUT is also synchronized to EXTAL. If the PLL is disabled, the CLKOUT frequency is half the frequency of EXTAL.
PCAP	Input	Input	**PLL Capacitor**—An input connecting an off-chip capacitor to the PLL filter. Connect one capacitor terminal to PCAP and the other terminal to V_{CCP}. If the PLL is not used, PCAP can be tied to V_{CC}, GND, or left floating.
PINIT $\overline{\text{NMI}}$	Input Input	Input	**PLL Initial**—During assertion of $\overline{\text{RESET}}$, the value of PINIT is written into the PLL enable (PEN) bit of the PLL control (PCTL) register, determining whether the PLL is enabled or disabled. **Nonmaskable Interrupt**—After $\overline{\text{RESET}}$ deassertion and during normal instruction processing, this Schmitt-trigger input is the negative-edge-triggered NMI request internally synchronized to CLKOUT. **Note**: PINIT/$\overline{\text{NMI}}$ can tolerate 5 V.

Table 1-11. Host Interface (Continued)

Signal Name	Type	State During Reset[1,2]	Signal Description
HRW	Input	Ignored Input	**Host Read/Write**—When the HI08 is programmed to interface with a single-data-strobe host bus and the HI function is selected, this signal is the Host Read/Write (HRW) input.
$\overline{\text{HRD}}$/HRD	Input		**Host Read Data**—When the HI08 is programmed to interface with a double-data-strobe host bus and the HI function is selected, this signal is the HRD strobe Schmitt-trigger input. The polarity of the data strobe is programmable but is configured as active-low ($\overline{\text{HRD}}$) after reset.
PB11	Input or Output		**Port B 11**—When the HI08 is configured as GPIO through the HI08 Port Control Register, this signal is individually programmed as an input or output through the HI08 Data Direction Register.
$\overline{\text{HDS}}$/HDS	Input	Ignored Input	**Host Data Strobe**—When the HI08 is programmed to interface with a single-data-strobe host bus and the HI function is selected, this signal is the host data strobe (HDS) Schmitt-trigger input. The polarity of the data strobe is programmable but is configured as active-low ($\overline{\text{HDS}}$) following reset.
$\overline{\text{HWR}}$/HWR	Input		**Host Write Data**—When the HI08 is programmed to interface with a double-data-strobe host bus and the HI function is selected, this signal is the host write data strobe (HWR) Schmitt-trigger input. The polarity of the data strobe is programmable but is configured as active-low ($\overline{\text{HWR}}$) following reset.
PB12	Input or Output		**Port B 12**—When the HI08 is configured as GPIO through the HI08 Port Control Register, this signal is individually programmed as an input or output through the HI08 Data Direction Register.
$\overline{\text{HREQ}}$/HREQ	Output	Ignored Input	**Host Request**—When the HI08 is programmed to interface with a single host request host bus and the HI function is selected, this signal is the host request (HREQ) output. The polarity of the host request is programmable but is configured as active-low ($\overline{\text{HREQ}}$) following reset. The host request may be programmed as a driven or open-drain output.
$\overline{\text{HTRQ}}$/HTRQ	Output		**Transmit Host Request**—When the HI08 is programmed to interface with a double host request host bus and the HI function is selected, this signal is the transmit host request (HTRQ) output. The polarity of the host request is programmable but is configured as active-low ($\overline{\text{HTRQ}}$) following reset. The host request may be programmed as a driven or open-drain output.
PB14	Input or Output		**Port B 14**—When the HI08 is configured as GPIO through the HI08 Port Control Register, this signal is individually programmed as an input or output through the HI08 Data Direction Register.

Table 1-13. Enhanced Serial Synchronous Interface 1 (Continued)

Signal Name	Type	State During Reset[1,2]	Signal Description
SC12	Input/Output	Ignored Input	**Serial Control Signal 2**—The frame sync for both the transmitter and receiver in synchronous mode and for the transmitter only in asynchronous mode. When configured as an output, this signal is the internally generated frame sync signal. When configured as an input, this signal receives an external frame sync signal for the transmitter (and the receiver in synchronous operation).
PD2	Input or Output		**Port D 2**—The default configuration following reset is GPIO input PD2. When configured as PD2, signal direction is controlled through the Port D Direction Register. The signal can be configured as an ESSI signal SC12 through the Port D Control Register.
SCK1	Input/Output	Ignored Input	**Serial Clock**—Provides the serial bit rate clock for the ESSI. The SCK1 is a clock input or output used by both the transmitter and receiver in synchronous modes or by the transmitter in asynchronous modes. Although an external serial clock can be independent of and asynchronous to the DSP system clock, it must exceed the minimum clock cycle time of 6T (that is, the system clock frequency must be at least three times the external ESSI clock frequency). The ESSI needs at least three DSP phases inside each half of the serial clock.
PD3	Input or Output		**Port D 3**—The default configuration following reset is GPIO input PD3. When configured as PD3, signal direction is controlled through the Port D Direction Register. The signal can be configured as an ESSI signal SCK1 through the Port D Control Register.
SRD1	Input	Ignored Input	**Serial Receive Data**—Receives serial data and transfers the data to the ESSI Receive Shift Register. SRD1 is an input when data is being received.
PD4	Input or Output		**Port D 4**—The default configuration following reset is GPIO input PD4. When configured as PD4, signal direction is controlled through the Port D Direction Register. The signal can be configured as an ESSI signal SRD1 through the Port D Control Register.
STD1	Output	Ignored Input	**Serial Transmit Data**—Transmits data from the Serial Transmit Shift Register. STD1 is an output when data is being transmitted.
PD5	Input or Output		**Port D 5**—The default configuration following reset is GPIO input PD5. When configured as PD5, signal direction is controlled through the Port D Direction Register. The signal can be configured as an ESSI signal STD1 through the Port D Control Register.

Notes:
1. In the Stop state, the signal maintains the last state as follows:
- If the last state is input, the signal is an ignored input.
- If the last state is output, the signal is tri-stated.

2. The Wait processing state does not affect the signal state.
3. All inputs are 5 V tolerant.

2.5 DC Electrical Characteristics

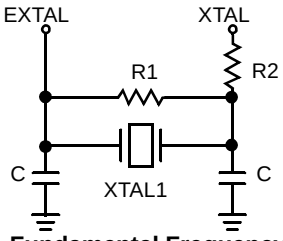
Table 2-3. DC Electrical Characteristics[6]

Characteristics	Symbol	Min	Typ	Max	Unit
Supply voltage	V_{CC}	3.0	3.3	3.6	V
Input high voltage					
• D[0–23], $\overline{BG}$, $\overline{BB}$, $\overline{TA}$	V_{IH}	2.0	—	V_{CC}	V
• MOD[1]/$\overline{IRQ}$[1], $\overline{RESET}$, PINIT/$\overline{NMI}$ and all JTAG/ESSI/SCI/Timer/HI08 pins	V_{IHP}	2.0	—	5.25	V
• EXTAL[8]	V_{IHX}	$0.8 \times V_{CC}$	—	V_{CC}	V
Input low voltage					
• D[0–23], $\overline{BG}$, $\overline{BB}$, $\overline{TA}$, MOD[1]/$\overline{IRQ}$[1], $\overline{RESET}$, PINIT	V_{IL}	–0.3	—	0.8	V
• All JTAG/ESSI/SCI/Timer/HI08 pins	V_{ILP}	–0.3	—	0.8	V
• EXTAL[8]	V_{ILX}	–0.3	—	$0.2 \times V_{CC}$	V
Input leakage current	I_{IN}	–10	—	10	µA
High impedance (off-state) input current (@ 2.4 V / 0.4 V)	I_{TSI}	–10	—	10	µA
Output high voltage	V_{OH}				
• TTL (I_{OH} = –0.4 mA)[5,7]		2.4	—	—	V
• CMOS (I_{OH} = –10 µA)[5]		V_{CC} – 0.01	—	—	V
Output low voltage	V_{OL}				
• TTL (I_{OL} = 1.6 mA, open-drain pins I_{OL} = 6.7 mA)[5,7]		—	—	0.4	V
• CMOS (I_{OL} = 10 µA)[5]		—	—	0.01	V
Internal supply current[2]:					
• In Normal mode	I_{CCI}	—	127	—	mA
• In Wait mode[3]	I_{CCW}	—	7.5	—	mA
• In Stop mode[4]	I_{CCS}	—	100	—	µA
PLL supply current		—	1	2.5	mA
Input capacitance[5]	C_{IN}	—	—	10	pF

Notes:
1. Refers to MODA/$\overline{IRQA}$, MODB/$\overline{IRQB}$, MODC/$\overline{IRQC}$, and MODD/$\overline{IRQD}$ pins.
2. **Power Consumption Considerations** on page Section 4-3 provides a formula to compute the estimated current requirements in Normal mode. In order to obtain these results, all inputs must be terminated (that is, not allowed to float). Measurements are based on synthetic intensive DSP benchmarks (see **Appendix A**). The power consumption numbers in this specification are 90 percent of the measured results of this benchmark. This reflects typical DSP applications. Typical internal supply current is measured with V_{CC} = 3.3 V at T_J = 100°C.
3. In order to obtain these results, all inputs must be terminated (that is, not allowed to float).
4. In order to obtain these results, all inputs that are not disconnected at Stop mode must be terminated (that is, not allowed to float). PLL and XTAL signals are disabled during Stop state.
5. Periodically sampled and not 100 percent tested.
6. V_{CC} = 3.3 V ± 0.3 V; T_J = –40°C to +100 °C, C_L = 50 pF
7. This characteristic does not apply to XTAL and PCAP.
8. Driving EXTAL to the low V_{IHX} or the high V_{ILX} value may cause additional power consumption (DC current). To minimize power consumption, the minimum V_{IHX} should be no lower than $0.9 \times V_{CC}$ and the maximum V_{ILX} should be no higher than $0.1 \times V_{CC}$.

2.6.2 External Clock Operation

The DSP56303 system clock is derived from the on-chip oscillator or is externally supplied. To use the on-chip oscillator, connect a crystal and associated resistor/capacitor components to EXTAL and XTAL; examples are shown in **Figure 2-1**.



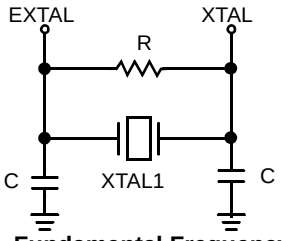
Fundamental Frequency Fork Crystal Oscillator

Note: Ensure that in the PCTL Register:
- XTLD (bit 16) = 0
- If $f_{OSC} \leq 200$ kHz, XTLR (bit 15) = 1

Suggested Component Values:

f_{OSC} = 32.768 kHz
R1 = 3.9 MΩ ± 10%
C = 22 pF ± 20%
R2 = 200 kΩ ± 10%

Calculations are for a 32.768 kHz crystal with the following parameters:
- load capacitance (C_L) of 12.5 pF,
- shunt capacitance (C_0) of 1.8 pF,
- series resistance of 40 kΩ, and
- drive level of 1 µW.



Fundamental Frequency Crystal Oscillator

Note: Ensure that in the PCTL Register:
- XTLD (bit 16) = 0
- If $f_{OSC} > 200$ kHz, XTLR (bit 15) = 0

Suggested Component Values:

f_{OSC} = 4 MHz	f_{OSC} = 20 MHz
R = 680 kΩ ± 10%	R = 680 kΩ ± 10%
C = 56 pF ± 20%	C = 22 pF ± 20%

Calculations are for a 4/20 MHz crystal with the following parameters:
- C_L of 30/20 pF,
- C_0 of 7/6 pF,
- series resistance of 100/20 Ω, and
- drive level of 2 mW.

Figure 2-1. Crystal Oscillator Circuits

If an externally-supplied square wave voltage source is used, disable the internal oscillator circuit during bootup by setting XTLD (PCTL Register bit 16 = 1—see the *DSP56303 User's Manual*). The external square wave source connects to EXTAL; XTAL is not physically connected to the board or socket. **Figure 2-2** shows the relationship between the EXTAL input and the internal clock and CLKOUT.

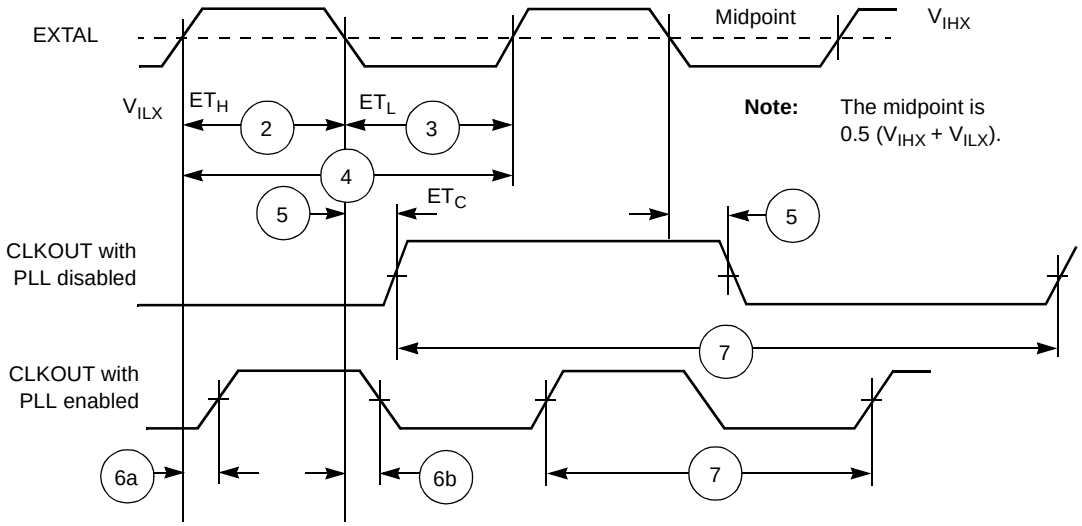


Figure 2-2. External Clock Timing

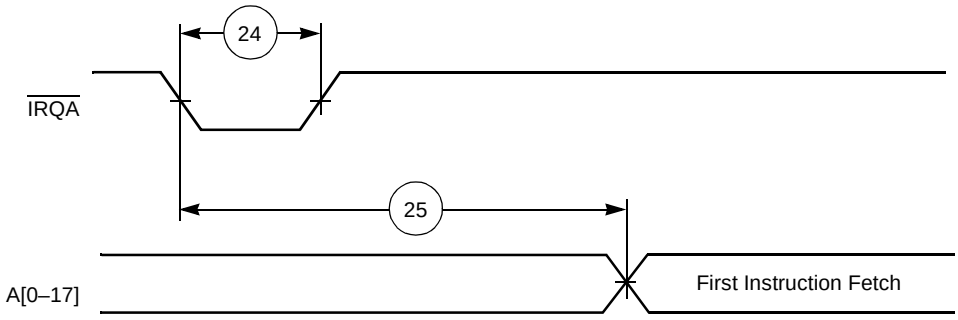


Figure 2-9. Recovery from Stop State Using $\overline{\text{IRQA}}$

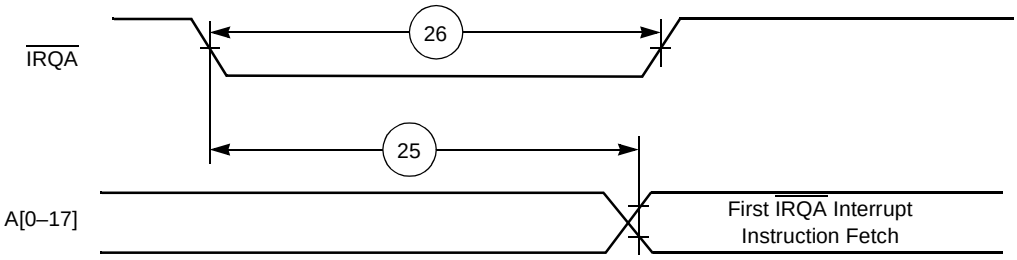


Figure 2-10. Recovery from Stop State Using $\overline{\text{IRQA}}$ Interrupt Service

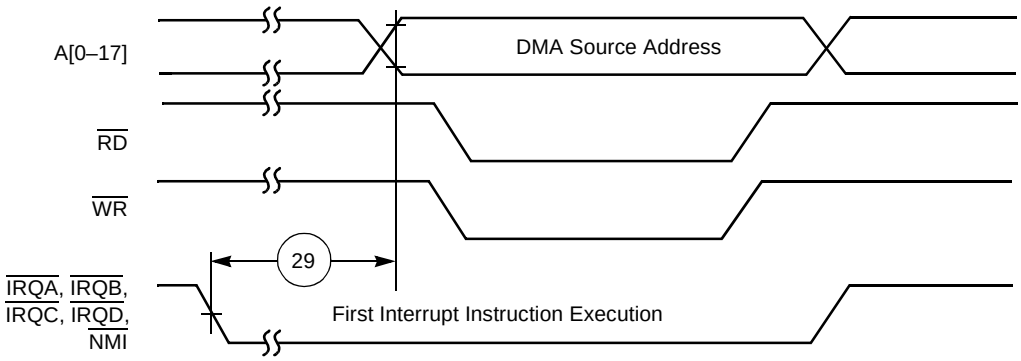


Figure 2-11. External Memory Access (DMA Source) Timing

2.6.5.2 DRAM Timing

The selection guides in **Figure 2-14** and **Figure 2-17** are for primary selection only. Final selection should be based on the timing in the following tables. For example, the selection guide suggests that four wait states must be used for 100 MHz operation with Page Mode DRAM. However, consulting the appropriate table, a designer can evaluate whether fewer wait states might suffice by determining which timing prevents operation at 100 MHz, running the chip at a slightly lower frequency (for example, 95 MHz), using faster DRAM (if it becomes available), and manipulating control factors such as capacitive and resistive load to improve overall system performance.

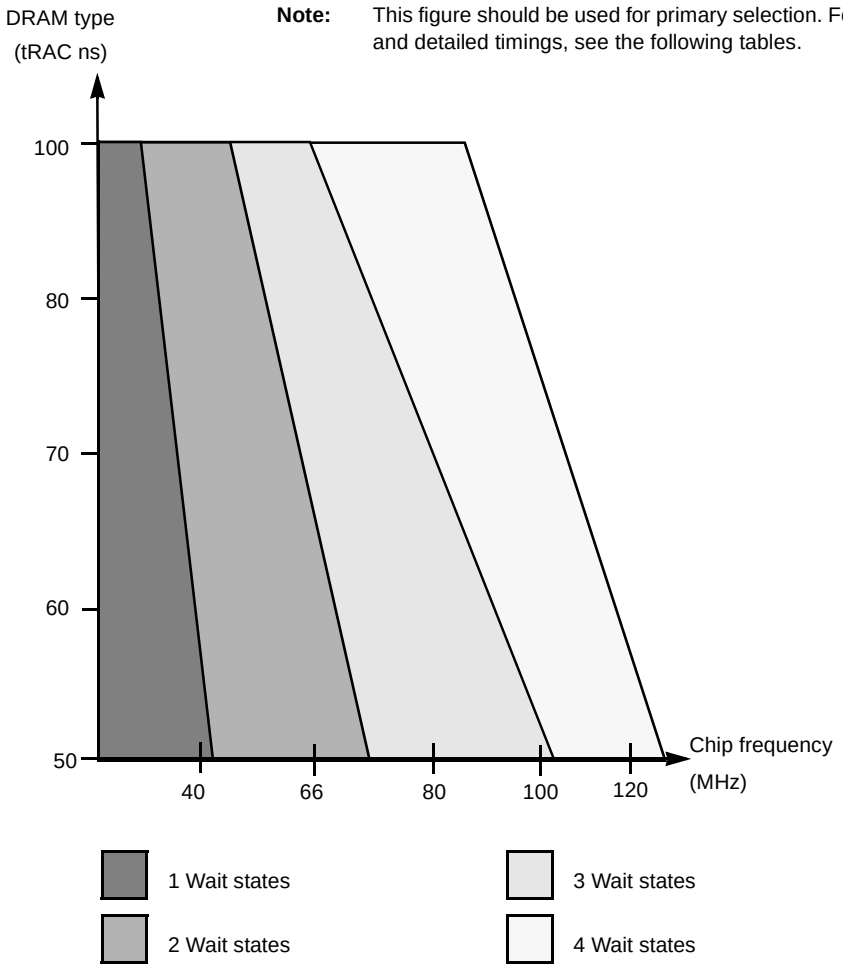


Figure 2-14. DRAM Page Mode Wait State Selection Guide

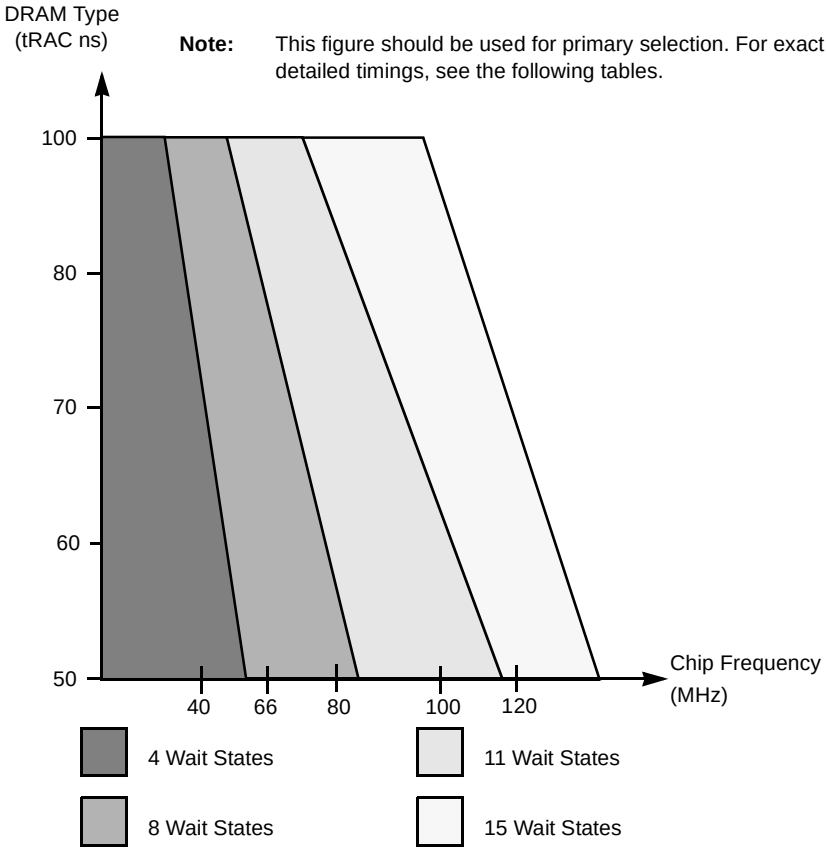


Figure 2-17. DRAM Out-of-Page Wait State Selection Guide

Table 2-11. DRAM Out-of-Page and Refresh Timings, Eleven Wait States[1,2]

No.	Characteristics	Symbol	Expression[3]	100 MHz		Unit
				Min	Max	
157	Random read or write cycle time	t_{RC}	$12 \times T_C$	120.0	—	ns
158	$\overline{RAS}$ assertion to data valid (read)	t_{RAC}	$6.25 \times T_C - 7.0$	—	55.5	ns
159	$\overline{CAS}$ assertion to data valid (read)	t_{CAC}	$3.75 \times T_C - 7.0$	—	30.5	ns
160	Column address valid to data valid (read)	t_{AA}	$4.5 \times T_C - 7.0$	—	38.0	ns
161	$\overline{CAS}$ deassertion to data not valid (read hold time)	t_{OFF}		0.0	—	ns
162	$\overline{RAS}$ deassertion to $\overline{RAS}$ assertion	t_{RP}	$4.25 \times T_C - 4.0$	38.5	—	ns
163	$\overline{RAS}$ assertion pulse width	t_{RAS}	$7.75 \times T_C - 4.0$	73.5	—	ns
164	$\overline{CAS}$ assertion to $\overline{RAS}$ deassertion	t_{RSH}	$5.25 \times T_C - 4.0$	48.5	—	ns
165	$\overline{RAS}$ assertion to $\overline{CAS}$ deassertion	t_{CSH}	$6.25 \times T_C - 4.0$	58.5	—	ns
166	$\overline{CAS}$ assertion pulse width	t_{CAS}	$3.75 \times T_C - 4.0$	33.5	—	ns
167	$\overline{RAS}$ assertion to $\overline{CAS}$ assertion	t_{RCD}	$2.5 \times T_C \pm 4.0$	21.0	29.0	ns
168	$\overline{RAS}$ assertion to column address valid	t_{RAD}	$1.75 \times T_C \pm 4.0$	13.5	21.5	ns
169	$\overline{CAS}$ deassertion to $\overline{RAS}$ assertion	t_{CRP}	$5.75 \times T_C - 4.0$	53.5	—	ns
170	$\overline{CAS}$ deassertion pulse width	t_{CP}	$4.25 \times T_C - 6.0$	36.5	—	ns

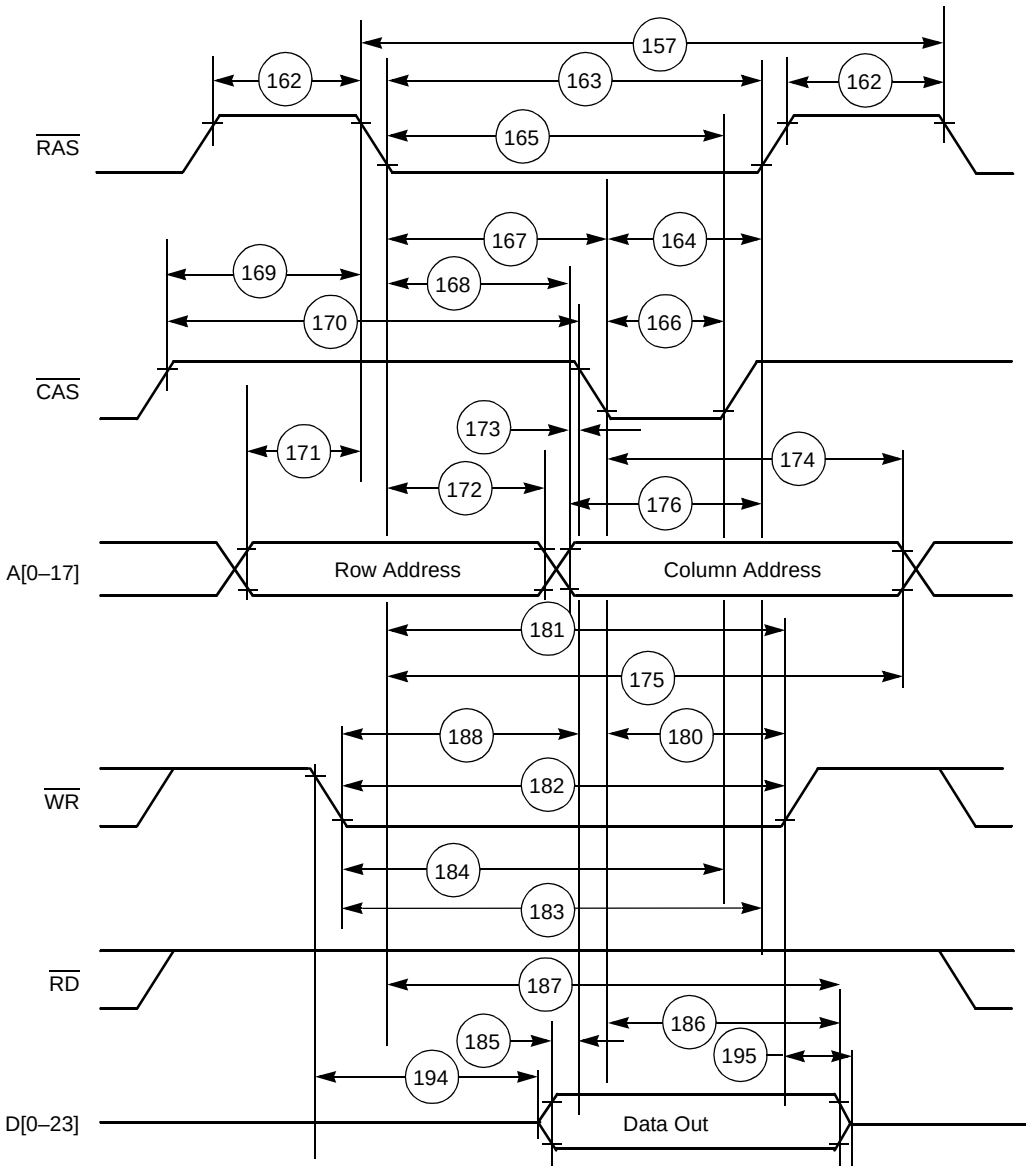


Figure 2-19. DRAM Out-of-Page Write Access

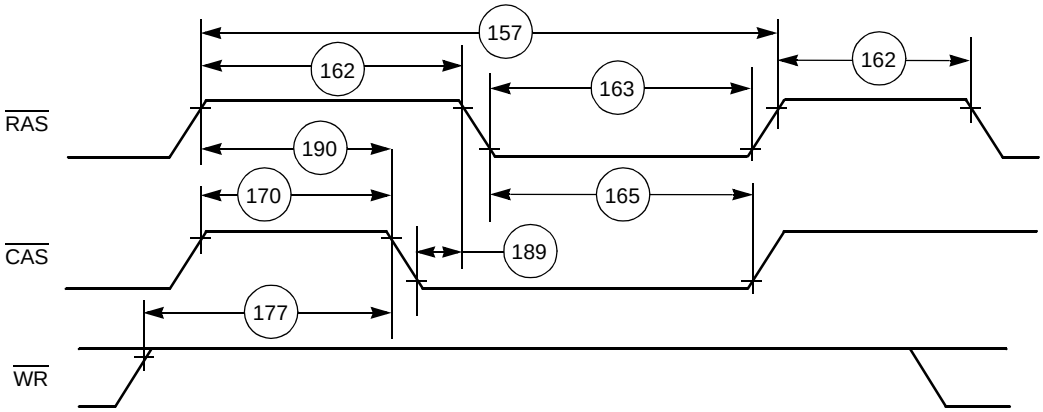
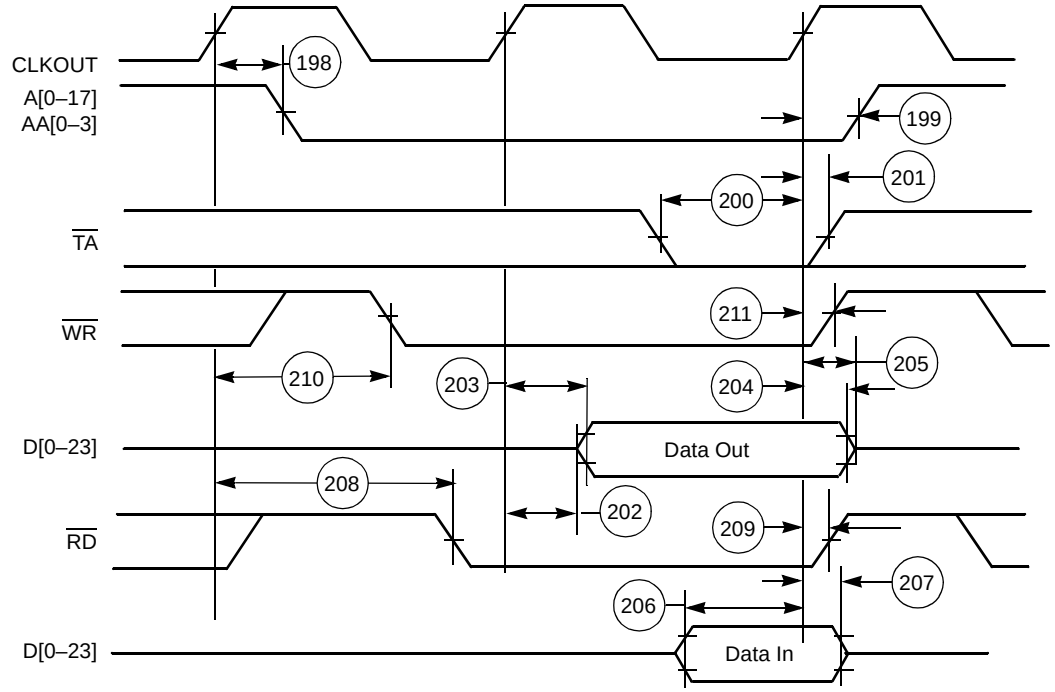
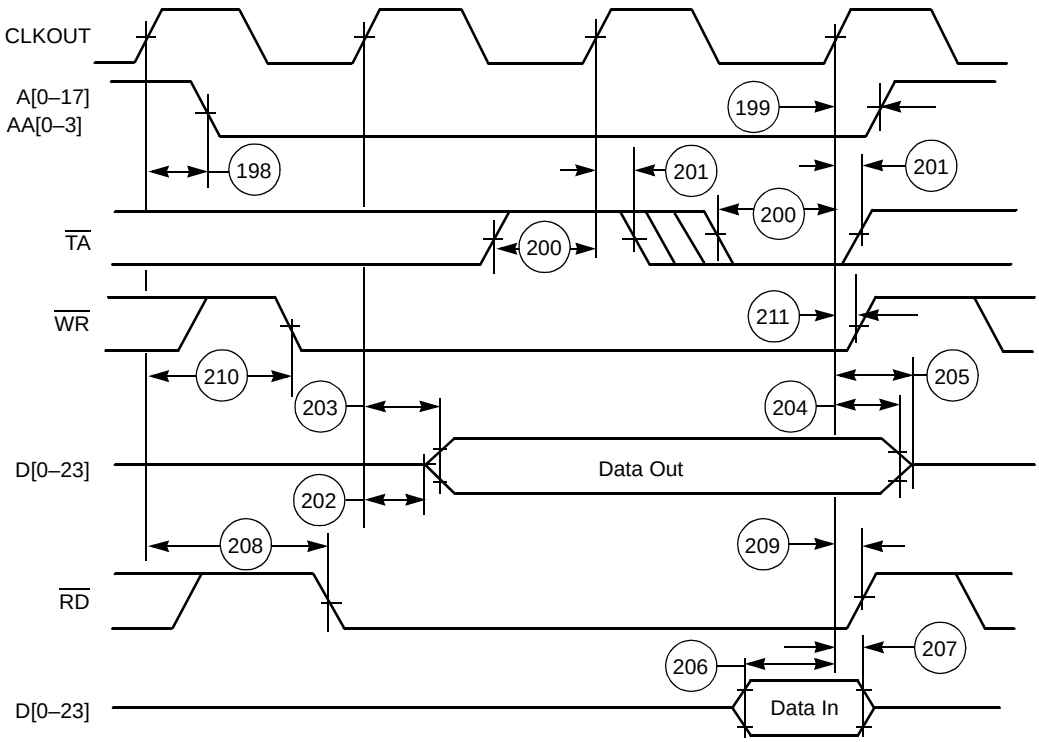


Figure 2-20. DRAM Refresh Access



Note: Address lines A[0–17] hold their state after a read or write operation. AA[0–3] do not hold their state after a read or write operation.

Figure 2-21. Synchronous Bus Timings 1 WS (BCR Controlled)



Note: Address lines A[0–17] hold their state after a read or write operation. AA[0–3] do not hold their state after a read or write operation.

Figure 2-22. Synchronous Bus Timings 2 WS ($\overline{TA}$ Controlled)

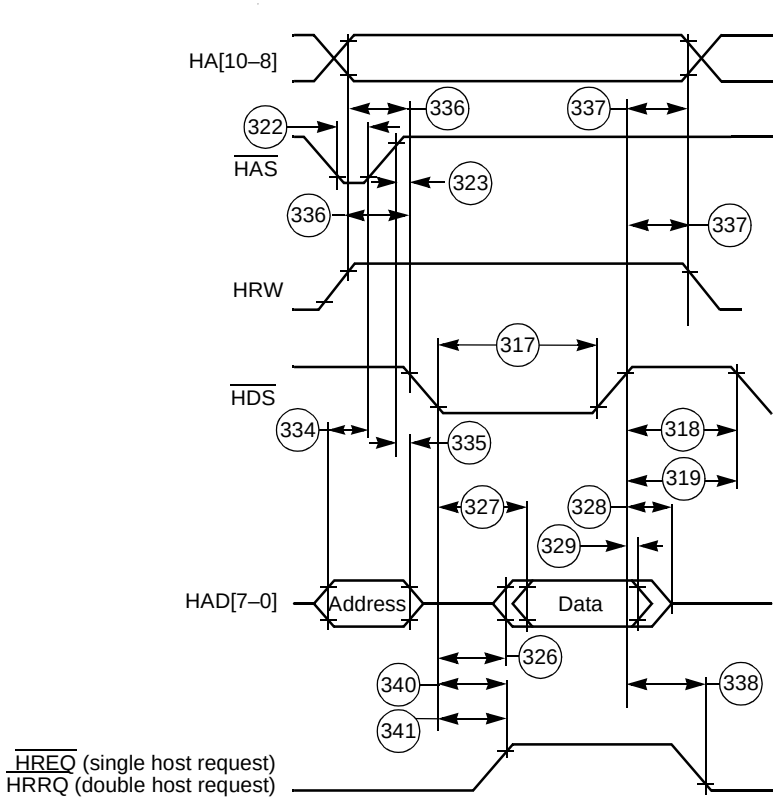


Figure 2-32. Read Timing Diagram, Multiplexed Bus, Single Data Strobe

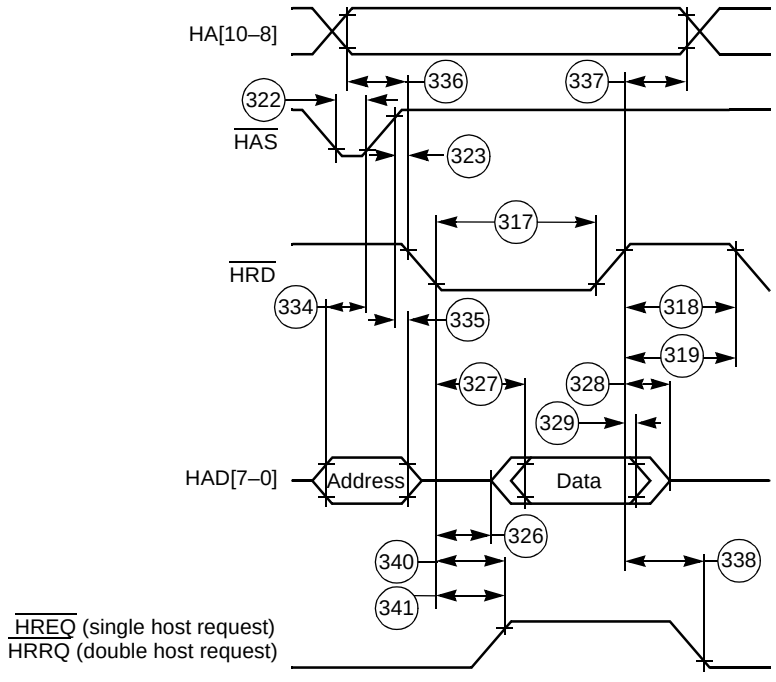


Figure 2-33. Read Timing Diagram, Multiplexed Bus, Double Data Strobe

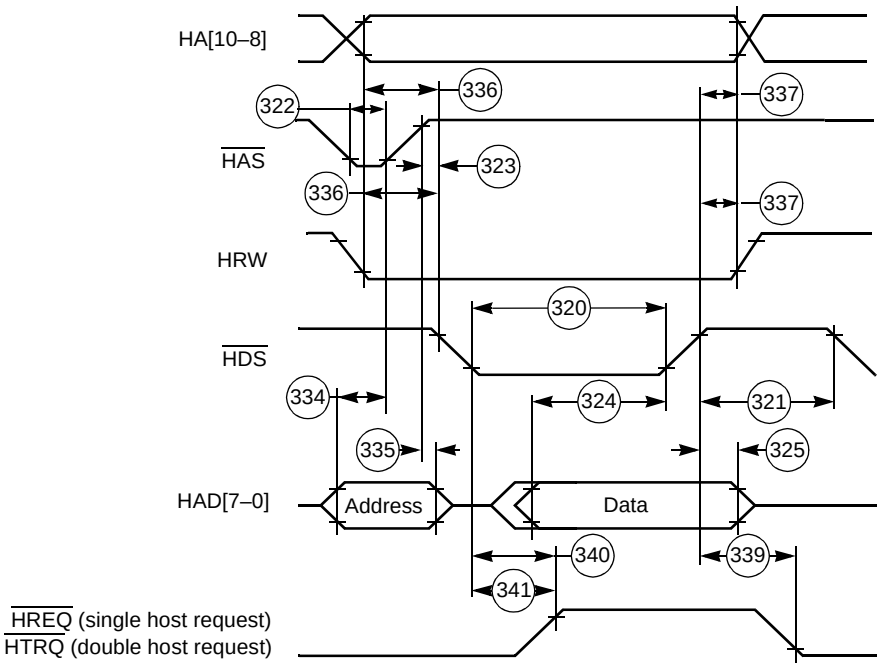


Figure 2-34. Write Timing Diagram, Multiplexed Bus, Single Data Strobe

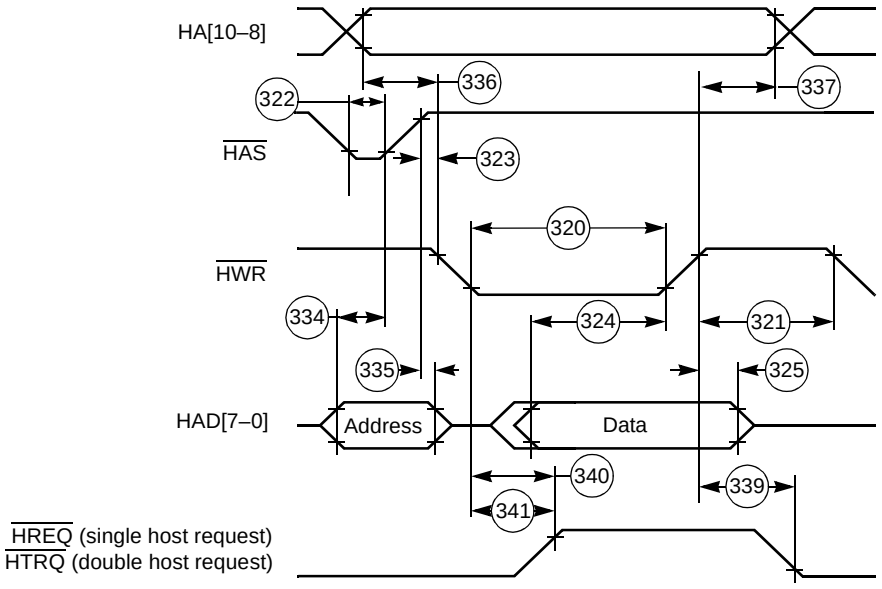
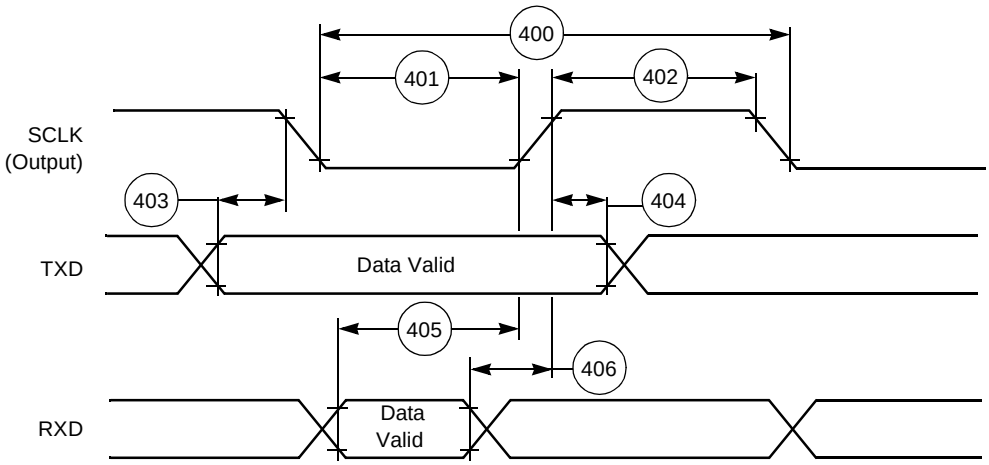
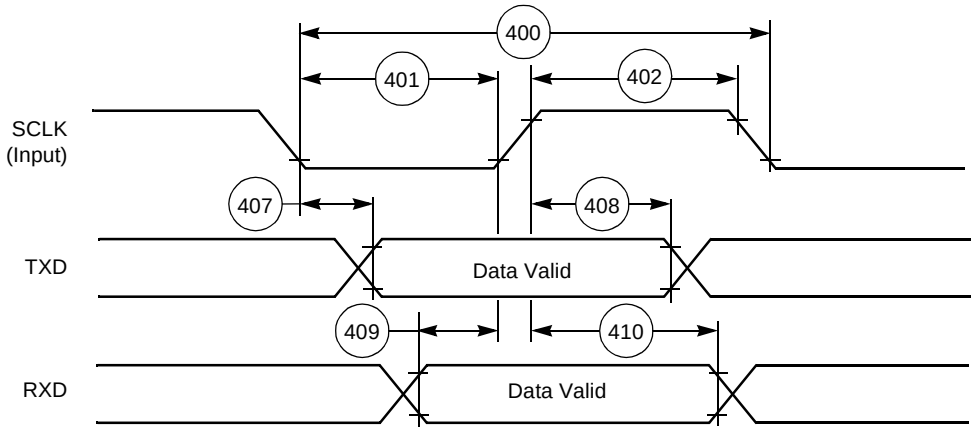


Figure 2-35. Write Timing Diagram, Multiplexed Bus, Double Data Strobe



a) Internal Clock



b) External Clock

Figure 2-36. SCI Synchronous Mode Timing

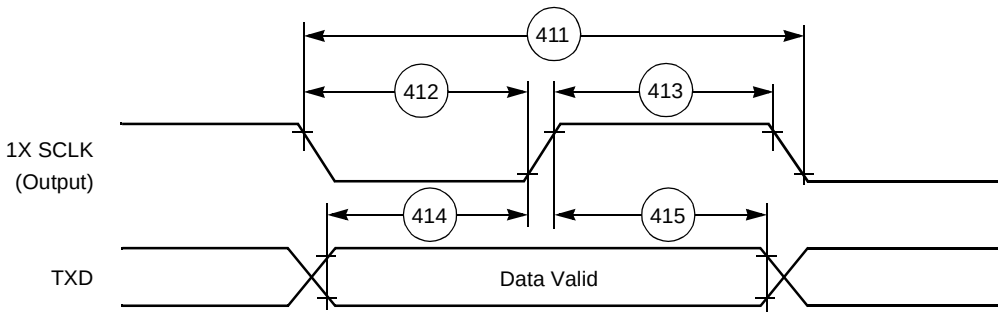


Figure 2-37. SCI Asynchronous Mode Timing

Table 2-18. ESSI Timings (Continued)

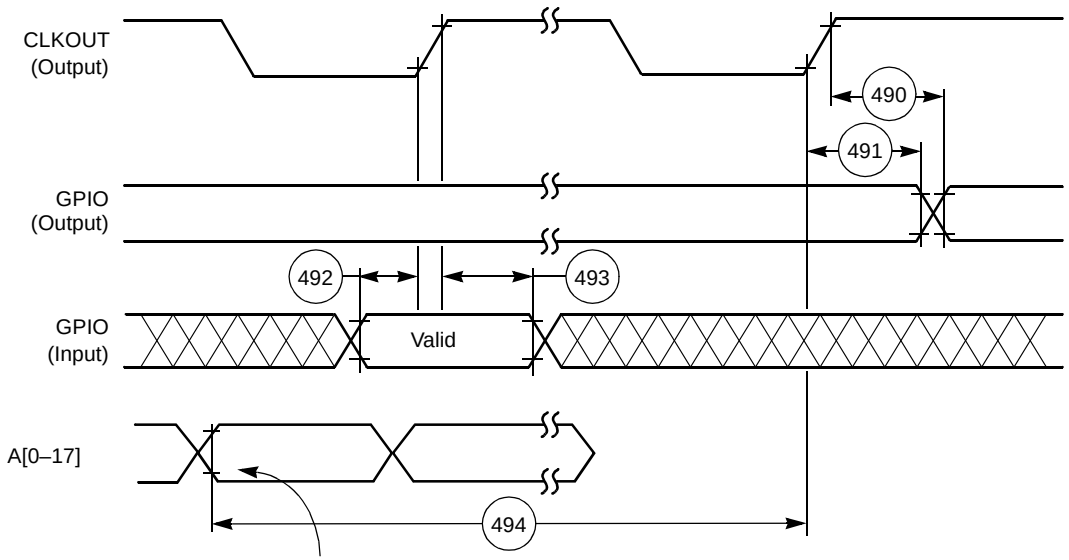
No.	Characteristics[4, 5, 7]	Symbol	Expression[9]	100 MHz		Cond-ition[5]	Unit
				Min	Max		
450	TXC rising edge to FST out (word-length) high			— —	30.0 16.0	x ck i ck	ns
451	TXC rising edge to FST out (word-length) low			— —	31.0 17.0	x ck i ck	ns
452	TXC rising edge to data out enable from high impedance			— —	31.0 17.0	x ck i ck	ns
453	TXC rising edge to Transmitter #0 drive enable assertion			— —	34.0 20.0	x ck i ck	ns
454	TXC rising edge to data out valid			— —	20.0[8] 10.0	x ck i ck	ns
455	TXC rising edge to data out high impedance[3]			— —	31.0 16.0	x ck i ck	ns
456	TXC rising edge to Transmitter #0 drive enable deassertion[3]			— —	34.0 20.0	x ck i ck	ns
457	FST input (bl, wr) setup time before TXC falling edge[2]			2.0 21.0	— —	x ck i ck	ns
458	FST input (wl) to data out enable from high impedance			—	27.0	—	ns
459	FST input (wl) to Transmitter #0 drive enable assertion			—	31.0	—	ns
460	FST input (wl) setup time before TXC falling edge			2.5 21.0	— —	x ck i ck	ns
461	FST input hold time after TXC falling edge			4.0 0.0	— —	x ck i ck	ns
462	Flag output valid after TXC rising edge			— —	32.0 18.0	x ck i ck	ns

Notes:
1. For the internal clock, the external clock cycle is defined by Icyc (see Timing 7) and the ESSI Control Register.
2. The word-length-relative frame sync signal waveform operates the same way as the bit-length frame sync signal waveform, but spreads from one serial clock before the first bit clock (same as the Bit Length Frame Sync signal) until the one before last bit clock of the first word in the frame.
3. Periodically sampled and not 100 percent tested
4. V_{CC} = 3.3 V ± 0.3 V; T_J = –40°C to +100 °C, C_L = 50 pF
5. TXC (SCK Pin) = Transmit Clock
   RXC (SC0 or SCK Pin) = Receive Clock
   FST (SC2 Pin) = Transmit Frame Sync
   FSR (SC1 or SC2 Pin) Receive Frame Sync
6. i ck = Internal Clock
   x ck = External Clock
   i ck a = Internal Clock, Asynchronous Mode
   (asynchronous implies that TXC and RXC are two different clocks)
   i ck s = Internal Clock, Synchronous Mode
   (synchronous implies that TXC and RXC are the same clock)
7. bl = bit length; wl = word length; wr = word length relative
8. If the DSP core writes to the transmit register during the last cycle before causing an underrun error, the delay is 20 ns + (0.5 × T_C).
9. An expression is used to compute the number listed as the minimum or maximum value as appropriate.

2.6.10 GPIO Timing

Table 2-20. GPIO Timing

No.	Characteristics	Expression	100 MHz		Unit
			Min	Max	
490	CLKOUT edge to GPIO out valid (GPIO out delay time)		—	8.5	ns
491	CLKOUT edge to GPIO out not valid (GPIO out hold time)		0.0	—	ns
492	GPIO In valid to CLKOUT edge (GPIO in set-up time)		8.5	—	ns
493	CLKOUT edge to GPIO in not valid (GPIO in hold time)		0.0	—	ns
494	Fetch to CLKOUT edge before GPIO change	Minimum: $6.75 \times T_C$	67.5	—	ns
Note:	$V_{CC} = 3.3\ V \pm 0.3\ V$; $T_J = -40°C$ to $+100\ °C$, $C_L = 50\ pF$				



Fetch the instruction MOVE X0,X:(R0); X0 contains the new value of GPIO and R0 contains the address of the GPIO data register.

Figure 2-43. GPIO Timing

Table 3-1. DSP56303 TQFP Signal Identification by Pin Number

Pin No.	Signal Name	Pin No.	Signal Name	Pin No.	Signal Name
1	SRD1 or PD4	26	GND_S	51	AA2/$\overline{RAS2}$
2	STD1 or PD5	27	TIO2	52	$\overline{CAS}$
3	SC02 or PC2	28	TIO1	53	XTAL
4	SC01 or PC1	29	TIO0	54	GND_Q
5	$\overline{DE}$	30	$\overline{HCS}$/HCS, HA10, or PB13	55	EXTAL
6	PINIT/$\overline{NMI}$	31	HA2, HA9, or PB10	56	V_{CCQ}
7	SRD0 or PC4	32	HA1, HA8, or PB9	57	V_{CCC}
8	V_{CCS}	33	HA0, $\overline{HAS}$/HAS, or PB8	58	GND_C
9	GND_S	34	H7, HAD7, or PB7	59	CLKOUT
10	STD0 or PC5	35	H6, HAD6, or PB6	60	BCLK
11	SC10 or PD0	36	H5, HAD5, or PB5	61	$\overline{BCLK}$
12	SC00 or PC0	37	H4, HAD4, or PB4	62	$\overline{TA}$
13	RXD or PE0	38	V_{CCH}	63	$\overline{BR}$
14	TXD or PE1	39	GND_H	64	$\overline{BB}$
15	SCLK or PE2	40	H3, HAD3, or PB3	65	V_{CCC}
16	SCK1 or PD3	41	H2, HAD2, or PB2	66	GND_C
17	SCK0 or PC3	42	H1, HAD1, or PB1	67	$\overline{WR}$
18	V_{CCQ}	43	H0, HAD0, or PB0	68	$\overline{RD}$
19	GND_Q	44	$\overline{RESET}$	69	AA1/$\overline{RAS1}$
20	Not Connected (NC), reserved	45	V_{CCP}	70	AA0/$\overline{RAS0}$
21	$\overline{HDS}$/HDS, $\overline{HWR}$/HWR, or PB12	46	PCAP	71	$\overline{BG}$
22	HRW, $\overline{HRD}$/HRD, or PB11	47	GND_P	72	A0
23	$\overline{HACK}$/HACK, $\overline{HRRQ}$/HRRQ, or PB15	48	GND_{P1}	73	A1
24	$\overline{HREQ}$/HREQ, $\overline{HTRQ}$/HTRQ, or PB14	49	Not Connected (NC), reserved	74	V_{CCA}
25	V_{CCS}	50	AA3/$\overline{RAS3}$	75	GND_A

4.4 PLL Performance Issues

The following explanations should be considered as general observations on expected PLL behavior. There is no test that replicates these exact numbers. These observations were measured on a limited number of parts and were not verified over the entire temperature and voltage ranges.

4.4.1 Phase Skew Performance

The phase skew of the PLL is defined as the time difference between the falling edges of EXTAL and CLKOUT for a given capacitive load on CLKOUT, over the entire process, temperature and voltage ranges. As defined in **Figure 2-2**, *External Clock Timing*, on page 2-5 for input frequencies greater than 15 MHz and the MF ≤ 4, this skew is greater than or equal to 0.0 ns and less than 1.8 ns; otherwise, this skew is not guaranteed. However, for MF < 10 and input frequencies greater than 10 MHz, this skew is between –1.4 ns and +3.2 ns.

4.4.2 Phase Jitter Performance

The phase jitter of the PLL is defined as the variations in the skew between the falling edges of EXTAL and CLKOUT for a given device in specific temperature, voltage, input frequency, MF, and capacitive load on CLKOUT. These variations are a result of the PLL locking mechanism. For input frequencies greater than 15 MHz and MF ≤ 4, this jitter is less than ±0.6 ns; otherwise, this jitter is not guaranteed. However, for MF < 10 and input frequencies greater than 10 MHz, this jitter is less than ±2 ns.

4.4.3 Frequency Jitter Performance

The frequency jitter of the PLL is defined as the variation of the frequency of CLKOUT. For small MF (MF < 10) this jitter is smaller than 0.5 percent. For mid-range MF (10 < MF < 500) this jitter is between 0.5 percent and approximately 2 percent. For large MF (MF > 500), the frequency jitter is 2–3 percent.

4.5 Input (EXTAL) Jitter Requirements

The allowed jitter on the frequency of EXTAL is 0.5 percent. If the rate of change of the frequency of EXTAL is slow (that is, it does not jump between the minimum and maximum values in one cycle) or the frequency of the jitter is fast (that is, it does not stay at an extreme value for a long time), then the allowed jitter can be 2 percent. The phase and frequency jitter performance results are valid only if the input jitter is less than the prescribed values.

```
        clr     b
        move    #$0,x0
        move    #$0,x1
        move    #$0,y0
        move    #$0,y1
        bset    #4,omr          ; ebd
;
sbr     dor     #60,_end
        mac     x0,y0,a x:(r0)+,x1      y:(r4)+,y1
        mac     x1,y1,a x:(r0)+,x0      y:(r4)+,y0
        add     a,b
        mac     x0,y0,a x:(r0)+,x1
        mac     x1,y1,a                 y:(r4)+,y0
        move    b1,x:$ff
_end
        bra     sbr
        nop
        nop
        nop
        nop
PROG_END
        nop
        nop


XDAT_START
;       org     x:0
        dc      $262EB9
        dc      $86F2FE
        dc      $E56A5F
        dc      $616CAC
        dc      $8FFD75
        dc      $9210A
        dc      $A06D7B
        dc      $CEA798
        dc      $8DFBF1
        dc      $A063D6
        dc      $6C6657
        dc      $C2A544
        dc      $A3662D
        dc      $A4E762
        dc      $84F0F3
        dc      $E6F1B0
        dc      $B3829
        dc      $8BF7AE
        dc      $63A94F
        dc      $EF78DC
        dc      $242DE5
        dc      $A3E0BA
        dc      $EBAB6B
        dc      $8726C8
        dc      $CA361
        dc      $2F6E86
        dc      $A57347
        dc      $4BE774
        dc      $8F349D
        dc      $A1ED12
        dc      $4BFCE3
        dc      $EA26E0
        dc      $CD7D99
        dc      $4BA85E
        dc      $27A43F
        dc      $A8B10C
        dc      $D3A55
        dc      $25EC6A
        dc      $2A255B
        dc      $A5F1F8
        dc      $2426D1
        dc      $AE6536
        dc      $CBBC37
        dc      $6235A4
        dc      $37F0D
        dc      $63BEC2
        dc      $A5E4D3
        dc      $8CE810
        dc      $3FF09
        dc      $60E50E
        dc      $CFFB2F
        dc      $40753C
        dc      $8262C5
        dc      $CA641A
```

S

T

W

X

Y